



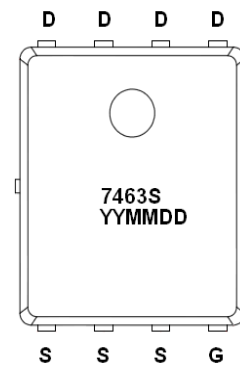
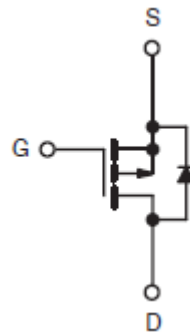
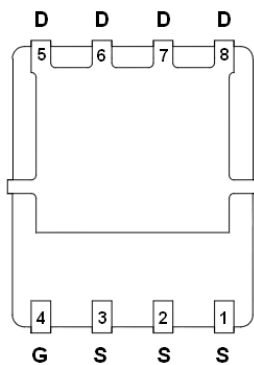
General Description

AFP7463S, P-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent $R_{DS(ON)}$, low gate charge. These devices are particularly suited for low voltage power management, and low in-line power loss are needed in commercial industrial surface mount applications.

Features

- -40V/-15A, $R_{DS(ON)}=12m\Omega@V_{GS}=-10V$
- -40V/-10A, $R_{DS(ON)}=15m\Omega@V_{GS}=-4.5V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- DFN5X6-8L package design

Pin Description (DFN5X6-8L)



Application

- Load Switch
- Adaptor Switch
- Notebook PC

Pin Define

Pin	Symbol	Description
4	G	Gate
1~3	S	Source
5~8	D	Drain

Ordering Information

Part Ordering No.	Part Marking	Package	Unit	Quantity
AFP7463SFN568RG	7463S	DFN5X6-8L	Tape & Reel	2500 EA

- ※ 7463S : Parts Code
- ※ YYMMDD : Date code
- ※ AFP7463SFN568RG : 13" Tape & Reel ; Pb- Free ; Halogen- Free



Absolute Maximum Ratings

(T_A=25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	V _{DSS}	-40	V
Gate –Source Voltage	V _{GSS}	±20	V
Continuous Drain Current(T _J =150°C)	I _{DSM}	T _A =25°C	-17
		T _A =70°C	-14
Pulsed Drain Current	I _{DM}	-65	A
Continuous Source Current(Diode Conduction)	I _S	-4.0	
Single Pulse Avalanche Current	I _{AS}	-25	
Power Dissipation	P _{DSM}	T _A =25°C	4.2
		T _A =75°C	2.7
Operating Junction Temperature	T _J	150	°C
Storage Temperature Range	T _{STG}	-55/150	°C
Thermal Resistance-Junction to Ambient	t ≤ 10 s	R _{θJA}	20
Thermal Resistance-Junction to Case	Steady-State	R _{θJC}	2.1

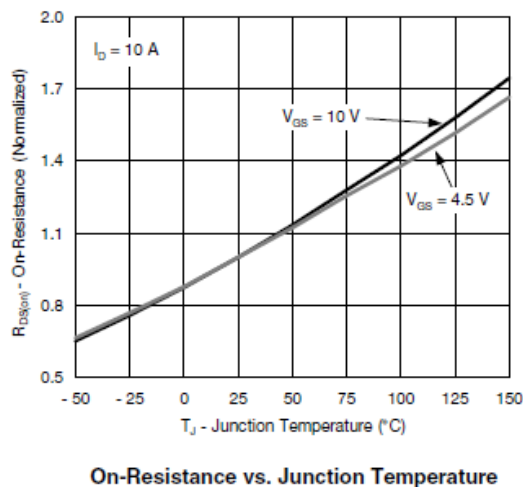
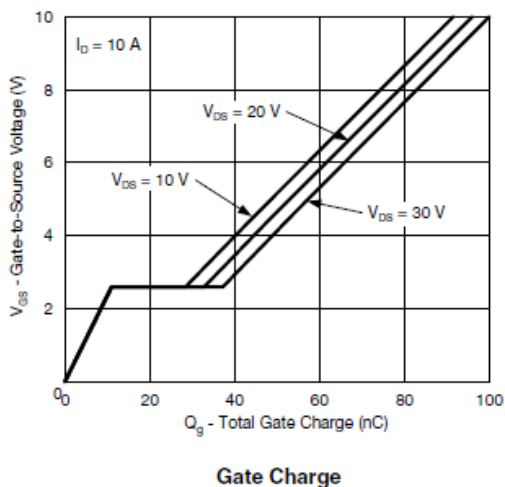
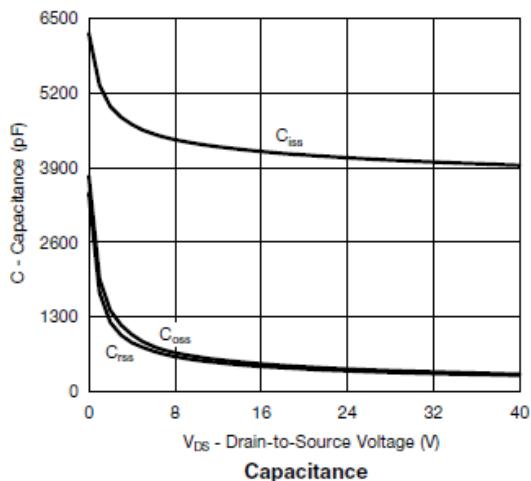
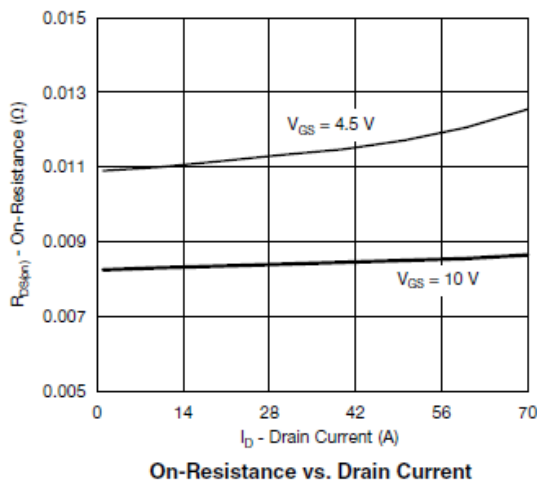
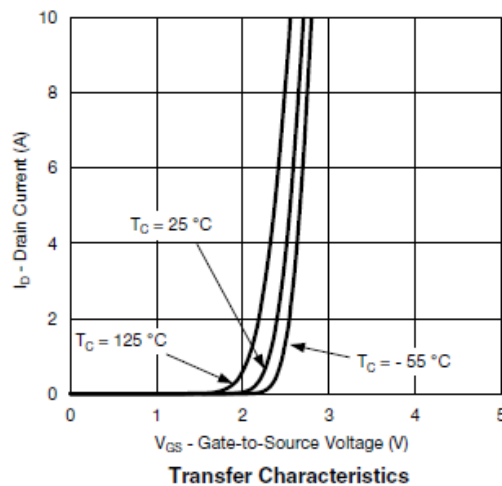
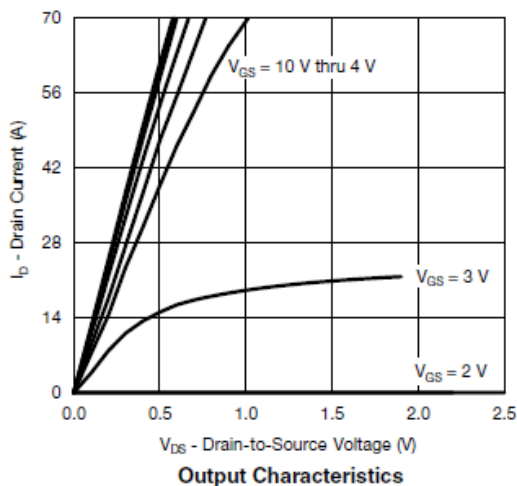
Electrical Characteristics

(T_A=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D = -250uA	-40			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D = -250uA	-1.0		-2.0	
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} = ±20V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -32V, V _{GS} =0V			-1	uA
		V _{DS} = -32V, V _{GS} =0V T _J =85°C			-20	
On-State Drain Current	I _{D(on)}	V _{DS} ≥ -10V, V _{GS} = -10V	-25			A
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = -10V, I _D = -15A		10	12	mΩ
		V _{GS} = -4.5V, I _D = -10A		13	15	
Forward Transconductance	g _{FS}	V _{DS} = -10V, I _D = -15A		40		S
Diode Forward Voltage	V _{SD}	I _S = -1A, V _{GS} =0V		-0.8	-1.3	V
Dynamic						
Total Gate Charge	Q _g	V _{DS} =-20V, V _{GS} =-4.5V I _D = -10A		45	90	nC
Gate-Source Charge	Q _{gs}			10		
Gate-Drain Charge	Q _{gd}			20		
Input Capacitance	C _{iss}	V _{DS} =-20V, V _{GS} =0V f=1MHz		4150		pF
Output Capacitance	C _{oss}			435		
Reverse Transfer Capacitance	C _{rss}			400		
Turn-On Time	t _{d(on)}	V _{DD} =-20V, R _L =2Ω I _D =-10A, V _{GEN} =-10V R _G =1Ω		15	30	ns
	t _r			15	30	
Turn-Off Time	t _{d(off)}			55	110	
	t _f			12	25	

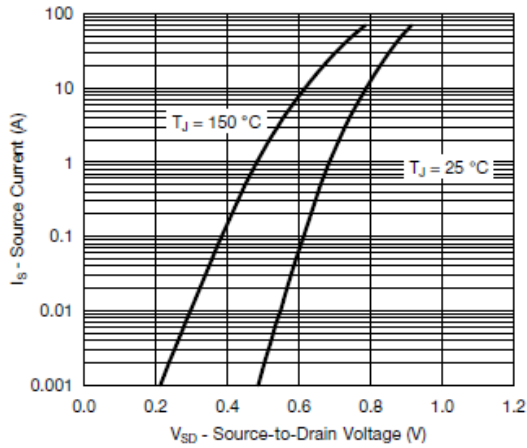


Typical Characteristics

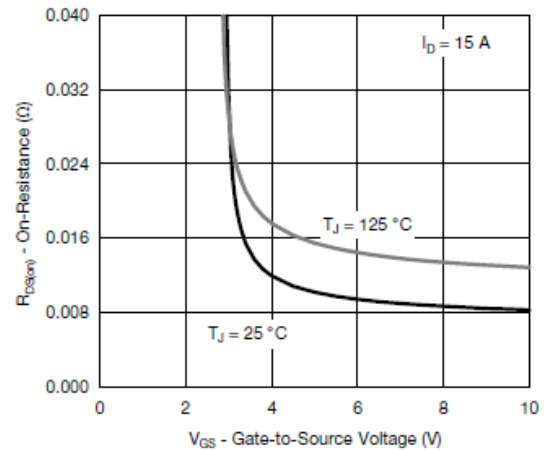




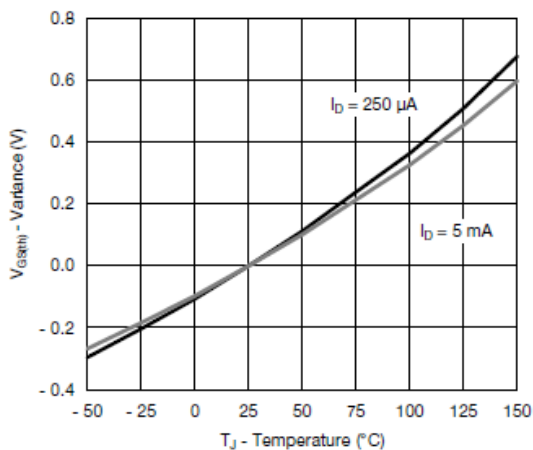
Typical Characteristics



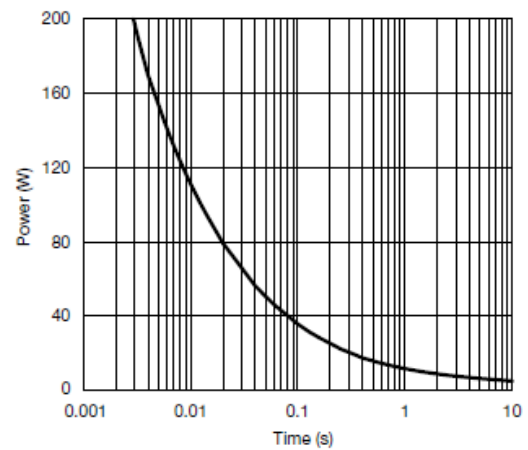
Source-Drain Diode Forward Voltage



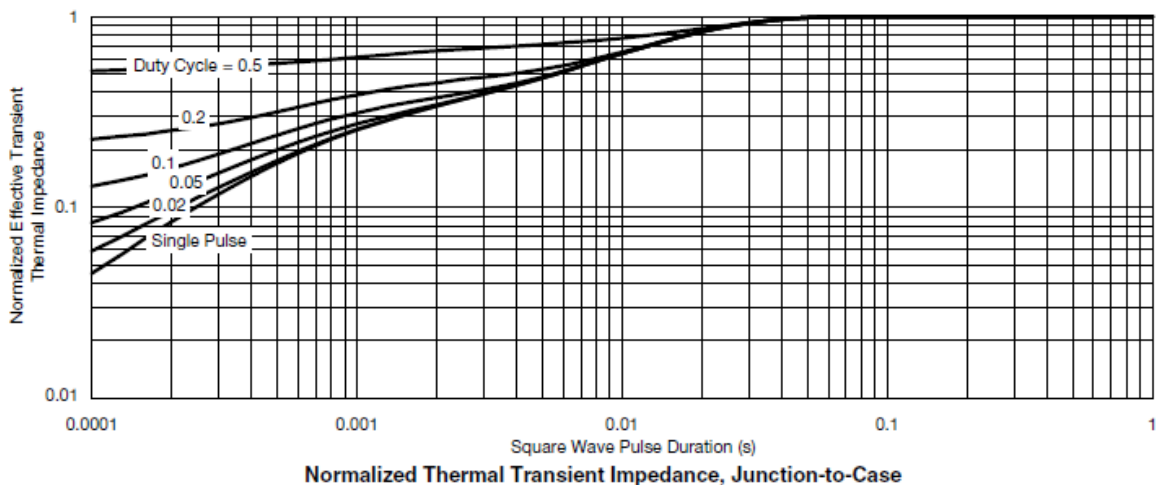
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power, Junction-to-Ambient

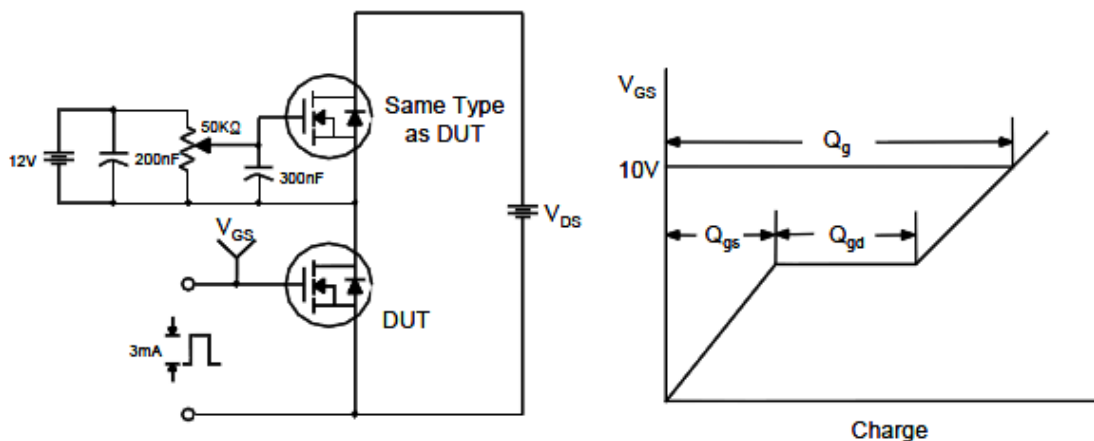


Normalized Thermal Transient Impedance, Junction-to-Case

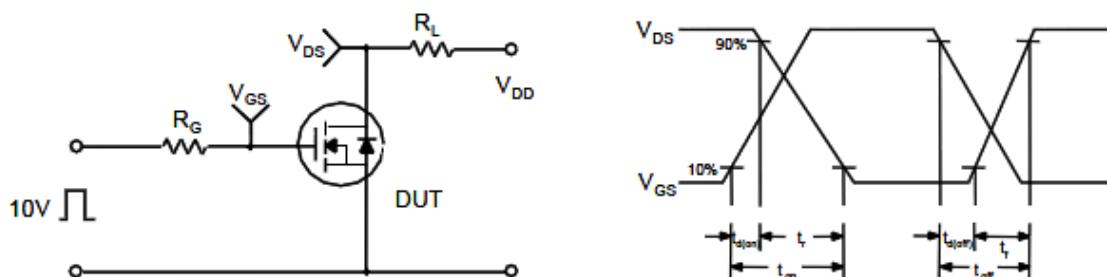


Typical Characteristics

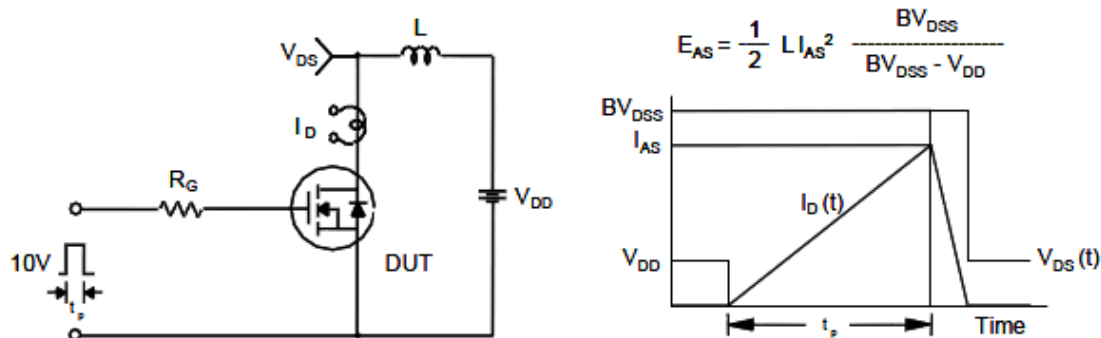
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

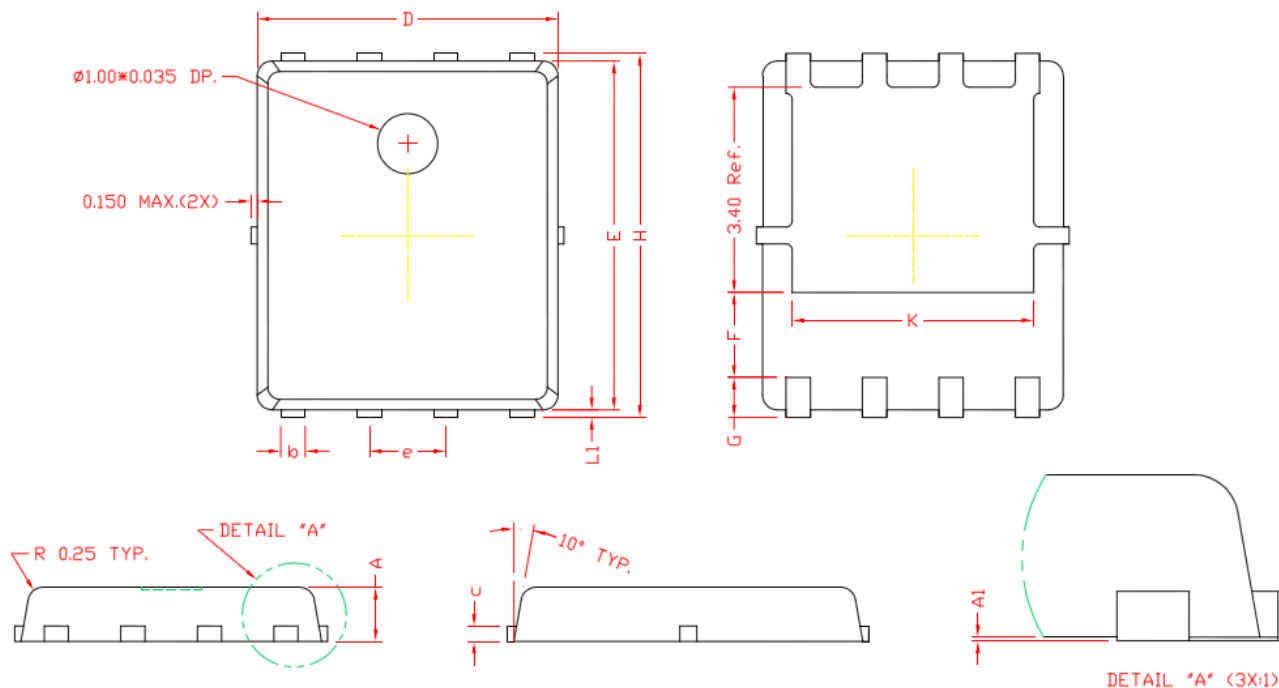


Unclamped Inductive Switching Test Circuit & Waveforms





Package Information (DFN5X6-8L)



DIMENSIONS

REF.	Millimeters		REF.	Millimeters	
	Min.	Max.		Min.	Max.
A	0.80	1.00	E	5.70	5.90
A1	0.00	0.05	e	1.27 BSC.	
b	0.35	0.49	H	5.95	6.20
c	0.254 Ref.		L1	0.10	0.18
D	4.90	5.10	G	0.60 Ref.	
F	1.40 Ref.		K	4.00 Ref.	

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